



US00D767233S

(12) **United States Design Patent** (10) **Patent No.:** **US D767,233 S**
Raschke et al. (45) **Date of Patent:** **** Sep. 20, 2016**

- (54) **WAFER CARRIER RING**
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- (**) Term: **14 Years**
- (21) Appl. No.: **29/518,509**
- (22) Filed: **Feb. 24, 2015**

Related U.S. Application Data

- (63) Continuation of application No. 29/430,855, filed on Aug. 30, 2012, now Pat. No. Des. 723,239.
- (51) **LOC (10) Cl.** **12-05**
- (52) **U.S. Cl.**
USPC **D34/29**
- (58) **Field of Classification Search**
USPC D34/29, 28; 198/851, 853, 825, 890.1, 198/370.1, 370.04, 782, 722, 771, 866, 367, 198/790; 193/35 A, 35 C; 414/744.5, 800
CPC H01L 21/67259; H01L 21/67742; H01L 21/67288; H02K 5/128
See application file for complete search history.

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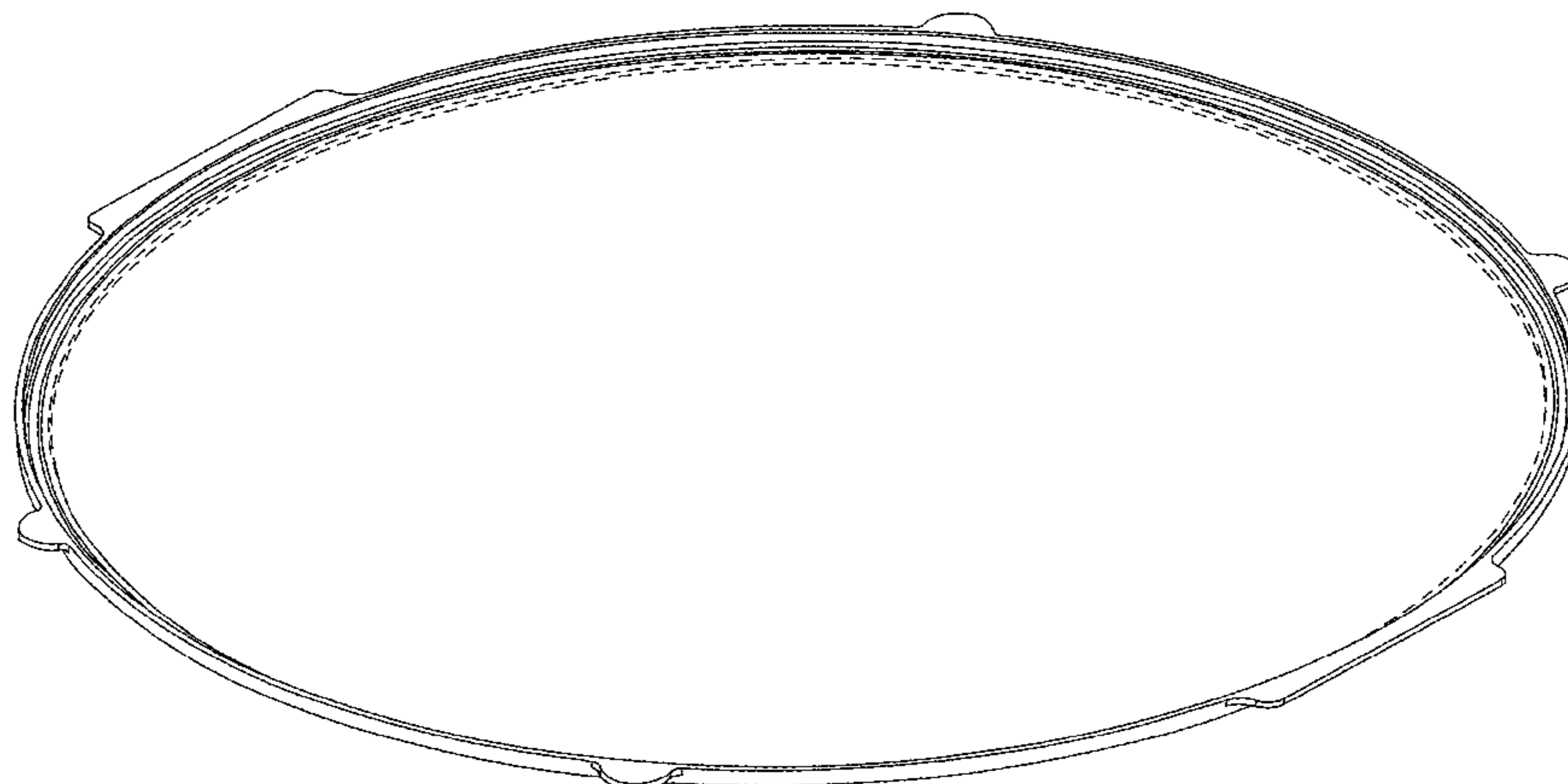
(57) **CLAIM**

The ornamental design for a wafer carrier ring, as shown and described.

DESCRIPTION

FIG. 1 is a top perspective view of a wafer carrier ring showing our new design;
 FIG. 2 is a bottom perspective view thereof;
 FIG. 3 is a top plan view thereof;
 FIG. 4 is a bottom plan view thereof;
 FIG. 5 is a front elevational view, with the rear being a mirror image thereof;
 FIG. 6 is a side elevational view, with the other side being a mirror image thereof;
 FIG. 7 is a cross sectional view taken at line 7-7 of FIG. 4 and,
 FIG. 8 is a cross sectional view taken at line 8-8 of FIG. 4. The broken lines shown in the figures are included for the purpose of illustrating portions of the wafer carrier ring and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



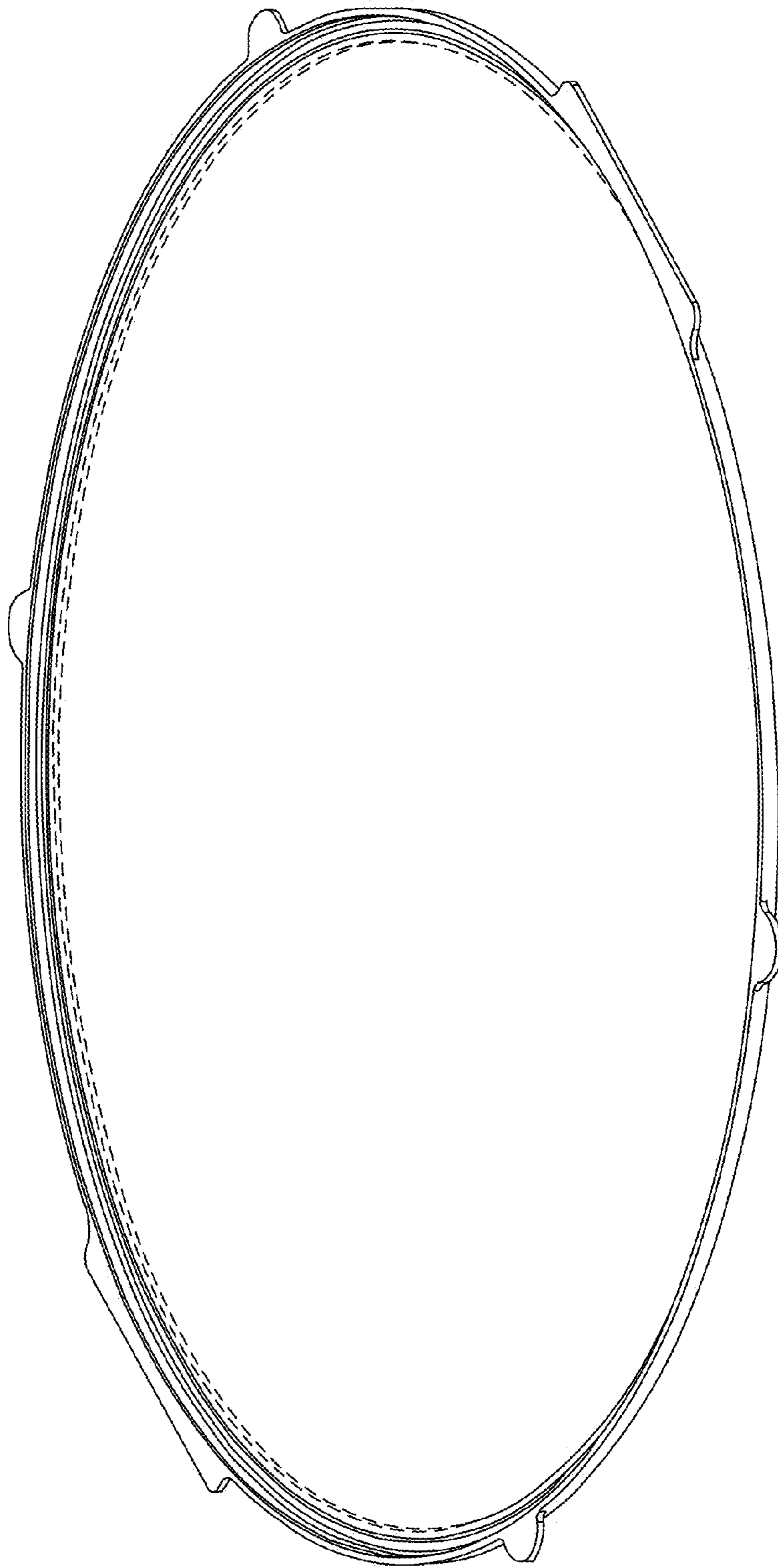


Fig. 1

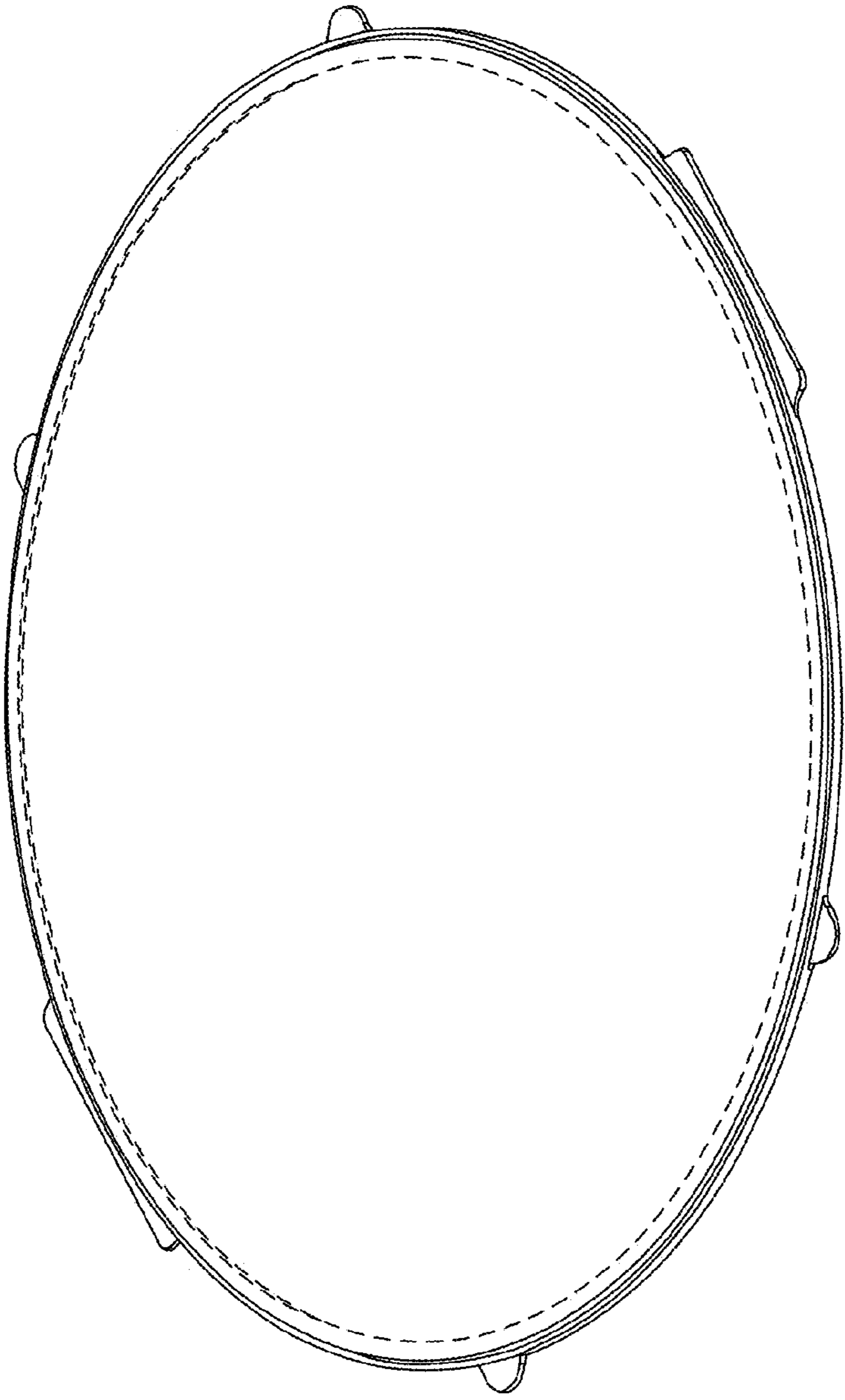


Fig. 2

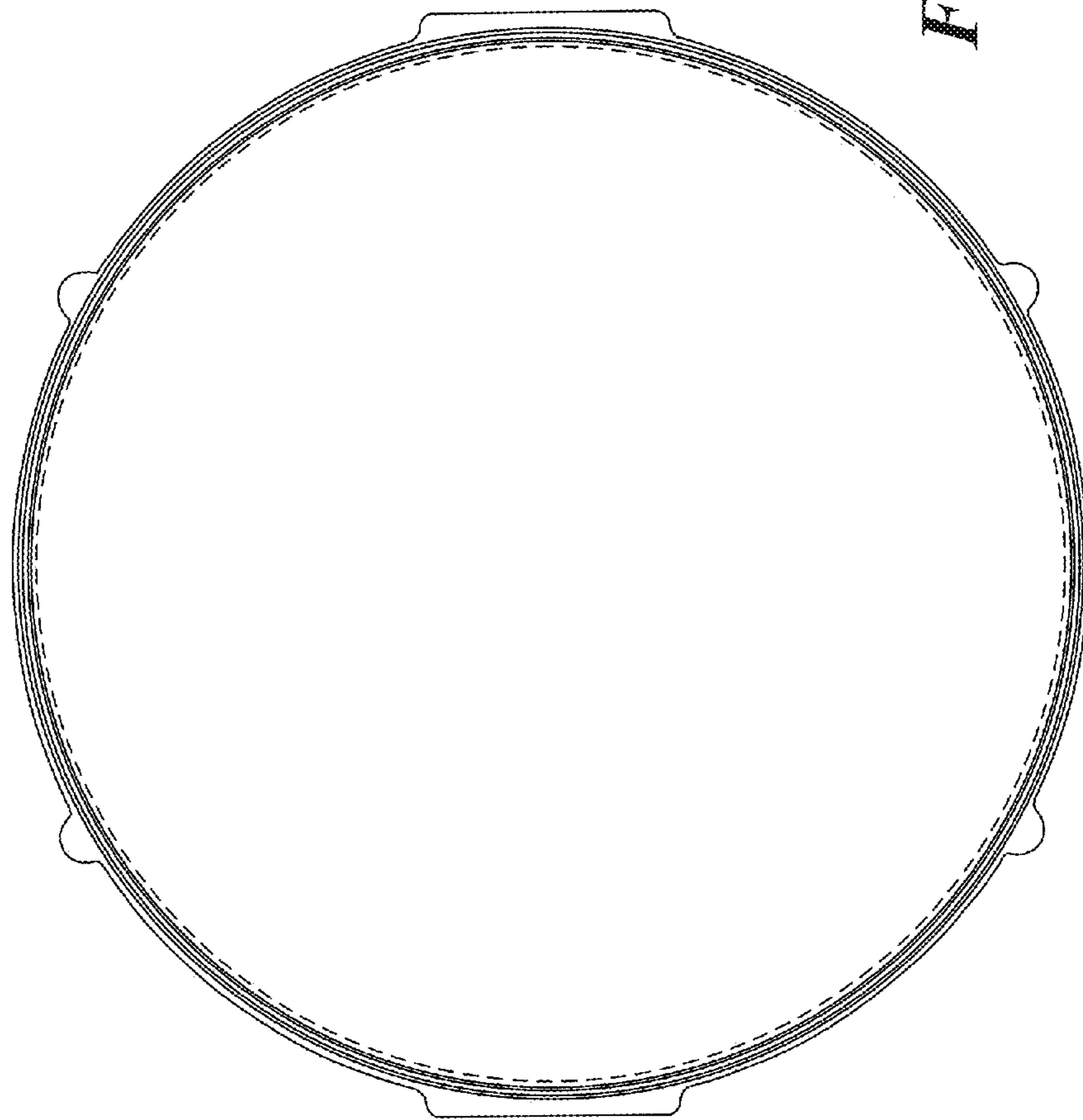


Fig. 3

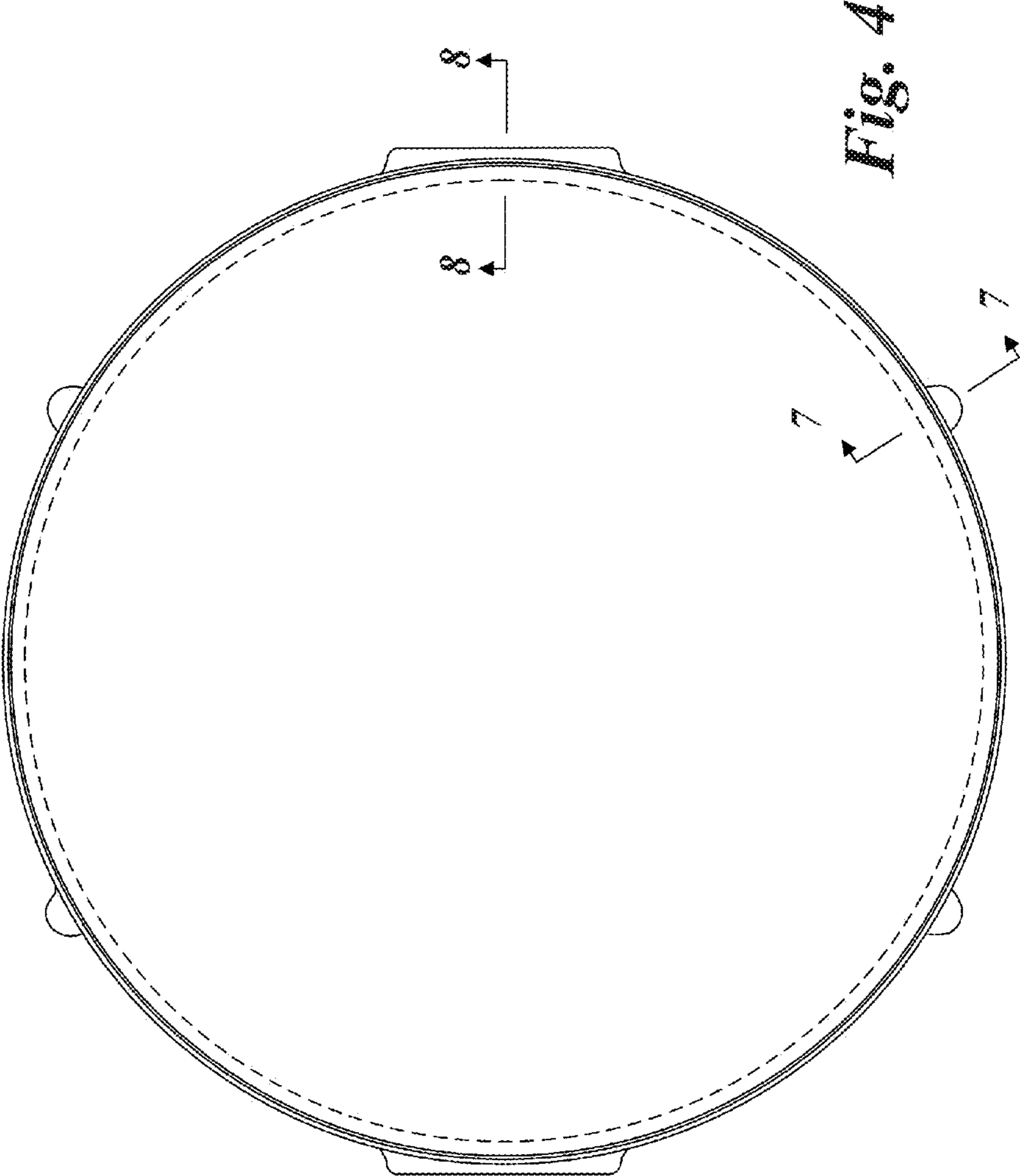


Fig. 4



Fig. 5

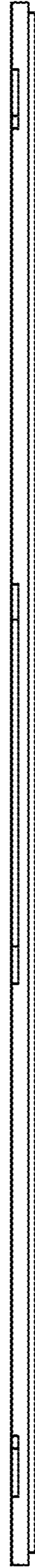


Fig. 6

Fig. 7

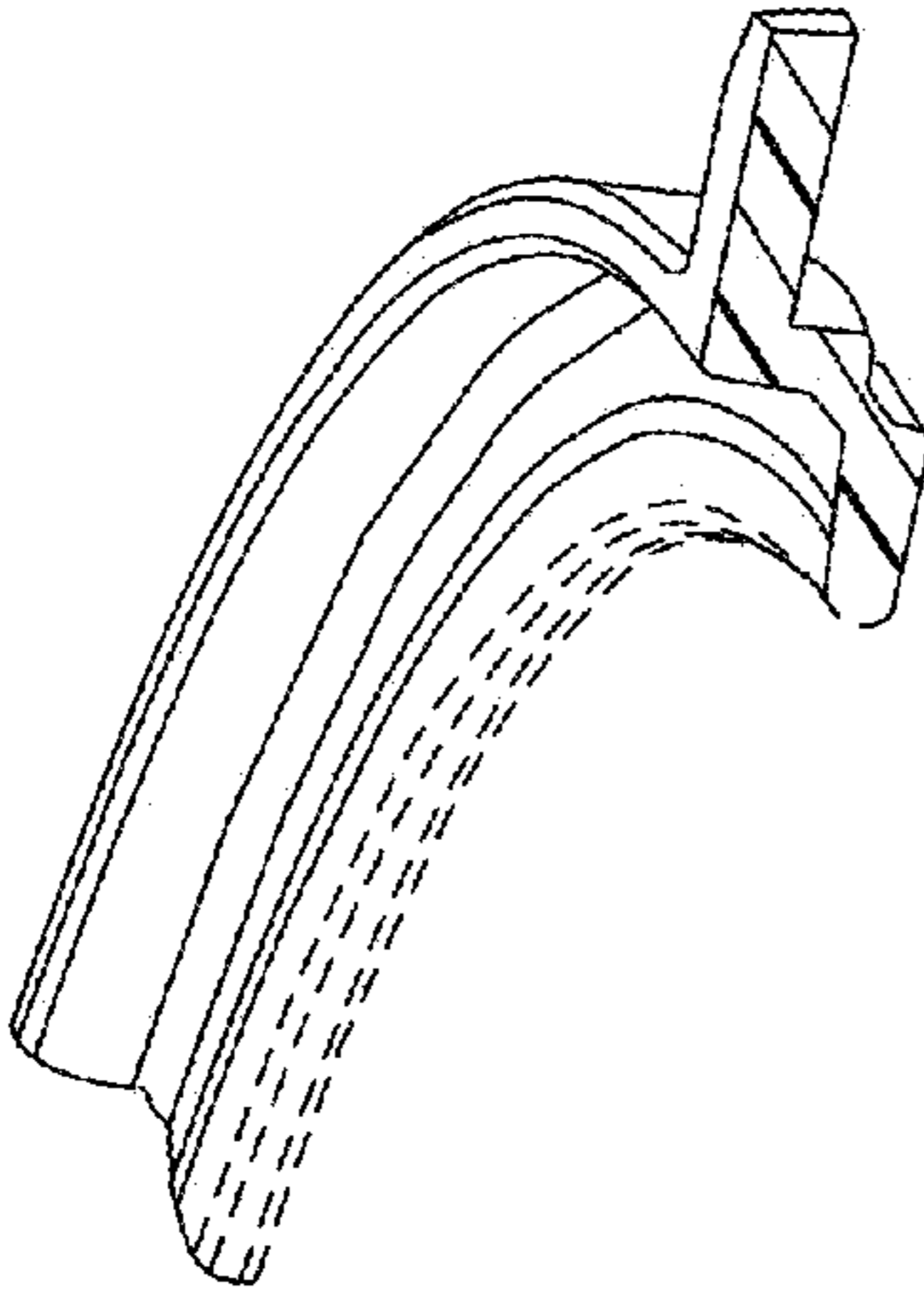


Fig. 8

